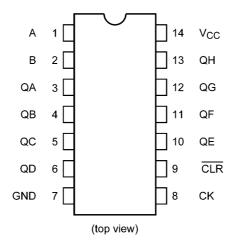
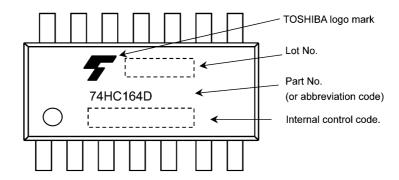


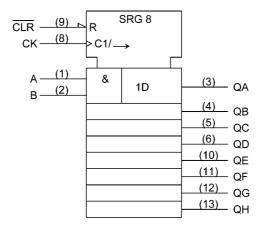
### 5. Pin Assignment



### 6. Marking



### 7. IEC Logic Symbol





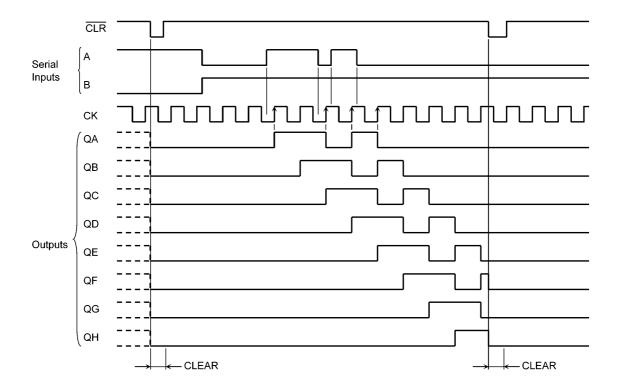
#### 8. Truth Table

	Inputs				Out	puts	
CLR	СК	Seri	Serial IN		QB		QH
CLK	CK	Α	В	QA	מט		QII
L	Х	Х	Х	L	L		L
Н		Х	Х		No CI	nange	
Н		L	Х	L	QAn		QGn
Н		Х	L	L	QAn		QGn
Н		Н	Н	Н	QAn		QGn

X: Don't care

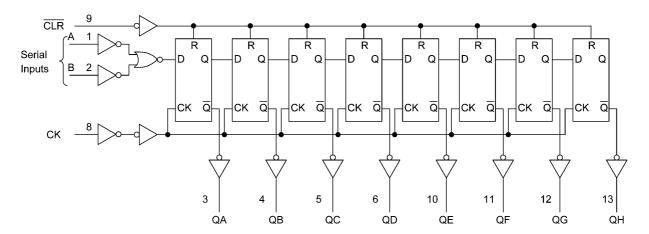
QAn to QGn: The level of QA to QG, respectively, before the most recent positive edge of the CK.

#### 9. Timing Diagrams





#### 10. System Diagram



#### 11. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Note	Rating	Unit
Supply voltage	V <sub>CC</sub>		-0.5 to 7.0	V
Input voltage	V <sub>IN</sub>		-0.5 to V <sub>CC</sub> + 0.5	V
Output voltage	V <sub>OUT</sub>		-0.5 to V <sub>CC</sub> + 0.5	V
Input diode current	I <sub>IK</sub>		±20	mA
Output diode current	I <sub>OK</sub>		±20	mA
Output current	I <sub>OUT</sub>		±25	mA
V <sub>CC</sub> /ground current	I <sub>CC</sub>		±50	mA
Power dissipation	P <sub>D</sub>	(Note 1)	500	mW
Storage temperature	T <sub>stg</sub>		-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: P<sub>D</sub> derates linearly with -8 mW/°C above 85 °C

#### 12. Operating Ranges (Note)

Characteristics	Symbol	Test Condition	Rating	Unit
Supply voltage	V <sub>CC</sub>		2.0 to 6.0	V
Input voltage	V <sub>IN</sub>		0 to V <sub>CC</sub>	V
Output voltage	V <sub>OUT</sub>		0 to V <sub>CC</sub>	٧
Operating temperature	T <sub>opr</sub>		-40 to 125	°C
Input rise and fall times	t <sub>r</sub> ,t <sub>f</sub>		0 to 50	μS

Note: The operating ranges must be maintained to ensure the normal operation of the device. Unused inputs must be tied to either  $V_{CC}$  or GND.



#### 13. Electrical Characteristics

## 13.1. DC Characteristics (Unless otherwise specified, $T_a$ = 25 °C)

Characteristics	Symbol	Test Condition	١	V <sub>CC</sub> (V)	Min	Тур.	Max	Unit
High-level input voltage	V <sub>IH</sub>	_		2.0	1.50	_	_	V
				4.5	3.15	_	_	
				6.0	4.20	_	_	
Low-level input voltage	V <sub>IL</sub>	_		2.0	_	_	0.50	V
				4.5			1.35	
				6.0			1.80	
High-level output voltage	V <sub>OH</sub>	$V_{IN} = V_{IH}$ or $V_{IL}$	I <sub>OH</sub> = -20 μA	2.0	1.9	2.0	_	V
				4.5	4.4	4.5	_	
				6.0	5.9	6.0	_	
			I <sub>OH</sub> = -4 mA	4.5	4.18	4.31	_	
			I <sub>OH</sub> = -5.2 mA	6.0	5.68	5.80	_	
Low-level output voltage	V <sub>OL</sub>	$V_{IN} = V_{IH}$ or $V_{IL}$	I <sub>OL</sub> = 20 μA	2.0	_	0.0	0.1	V
				4.5	_	0.0	0.1	
				6.0	_	0.0	0.1	
			I <sub>OL</sub> = 4 mA	4.5	_	0.17	0.26	
			I <sub>OL</sub> = 5.2 mA	6.0	_	0.18	0.26	
Input leakage current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND		6.0	_	_	±0.1	μА
Quiescent supply current	Icc	$V_{IN} = V_{CC}$ or GND		6.0	_	_	4.0	μΑ

## 13.2. DC Characteristics (Unless otherwise specified, $T_a$ = -40 to 85 °C)

Characteristics	Symbol	Test Condition	1	V <sub>CC</sub> (V)	Min	Max	Unit
High-level input voltage	V <sub>IH</sub>	_		2.0	1.50	_	V
				4.5	3.15	_	1
				6.0	4.20	_	
Low-level input voltage	V <sub>IL</sub>	_		2.0	_	0.50	V
				4.5	_	1.35	1
				6.0	_	1.80	
High-level output voltage	V <sub>OH</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2.0	1.9	_	V
				4.5	4.4	_	1
				6.0	5.9	_	
			I <sub>OH</sub> = -4 mA	4.5	4.13	_	1
			I <sub>OH</sub> = -5.2 mA	6.0	5.63	_	1
Low-level output voltage	V <sub>OL</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2.0	_	0.1	V
				4.5	_	0.1	1
				6.0	_	0.1	1
			I <sub>OL</sub> = 4 mA	4.5	_	0.33	
			I <sub>OL</sub> = 5.2 mA	6.0	_	0.33	] <b> </b>
Input leakage current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND		6.0	_	±1.0	μА
Quiescent supply current	I <sub>CC</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND		6.0	_	40.0	μА



### 13.3. DC Characteristics (Unless otherwise specified, $T_a$ = -40 to 125 °C)

Characteristics	Symbol	Test Condition	ı	V <sub>CC</sub> (V)	Min	Max	Unit
High-level input voltage	V <sub>IH</sub>	_		2.0	1.50	_	V
				4.5	3.15	_	
				6.0	4.20	_	
Low-level input voltage	V <sub>IL</sub>	_		2.0		0.50	V
				4.5		1.35	
				6.0		1.80	
High-level output voltage	V <sub>OH</sub>	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OH}$ = -20 $\mu$ A	2.0	1.9	ı	V
				4.5	4.4		
				6.5	5.9		
			$I_{OH}$ = -4 mA	4.5	3.7	ı	
			$I_{OH} = -5.2 \text{ mA}$	6.0	5.2		
Low-level output voltage	V <sub>OL</sub>	$V_{IN} = V_{IH}$ or $V_{IL}$	I <sub>OL</sub> = 20 μA	2.0	_	0.1	V
				4.5	_	0.1	
				6.0	_	0.1	
			I <sub>OL</sub> = 4 mA	4.5	_	0.4	
			I <sub>OL</sub> = 5.2 mA	6.0	_	0.4	
Input leakage current	I <sub>IN</sub>	$V_{IN} = V_{CC}$ or GND		6.0	_	±1.0	μА
Quiescent supply current	I <sub>CC</sub>	$V_{IN} = V_{CC}$ or GND		6.0	_	160	μА

## 13.4. Timing Requirements (Unless otherwise specified, $T_a$ = 25 °C, Input: $t_f$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Limit	Unit
Minimum pulse width (CK)	$t_{w(L)}, t_{w(H)}$	_	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum pulse width (CLR)	t <sub>w(L)</sub>	_	2.0	80	ns
			4.5	16	
			6.0	14	
Minimum setup time (A, B)	t <sub>S</sub>	_	2.0	50	ns
			4.5	10	
			6.0	9	
Minimum hold time (A, B)	t <sub>h</sub>	_	2.0	5	ns
			4.5	5	
			6.0	5	
Minimum removal time (CLR)	t <sub>rem</sub>	_	2.0	5	ns
			4.5	5	
			6.0	5	
Clock frequency	f	_	2.0	6	MHz
			4.5	31	
			6.0	36	



# 13.5. Timing Requirements (Unless otherwise specified, $T_a$ = -40 to 85 °C, Input: $t_f$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Limit	Unit
Minimum pulse width (CK)	$t_{w(L)}, t_{w(H)}$	_	2.0	95	ns
			4.5	19	
			6.0	16	
Minimum pulse width (CLR)	t <sub>w(L)</sub>	_	2.0	100	ns
			4.5	20	
			6.0	17	
Minimum setup time (A, B)	t <sub>S</sub>	_	2.0	65	ns
			4.5	13	
			6.0	11	
Minimum hold time (A, B)	t <sub>h</sub>	_	2.0	5	ns
			4.5	5	
			6.0	5	
Minimum removal time (CLR)	t <sub>rem</sub>	_	2.0	5	ns
			4.5	5	
			6.0	5	
Clock frequency	f	_	2.0	5	MHz
			4.5	25	
			6.0	29	

## 13.6. Timing Requirements (Unless otherwise specified, $T_a$ = -40 to 125 °C, Input: $t_f$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Limit	Unit
Minimum pulse width (CK)	$t_{w(L)}, t_{w(H)}$	_	2.0	120	ns
			4.5	24	
			6.0	20	
Minimum pulse width (CLR)	t <sub>w(L)</sub>	_	2.0	120	ns
			4.5	24	
			6.0	20	
Minimum setup time (A, B)	t <sub>S</sub>	_	2.0	90	ns
			4.5	18	
			6.0	15	
Minimum hold time (A, B)	t <sub>h</sub>	_	2.0	5	ns
			4.5	5	
			6.0	5	
Minimum removal time (CLR)	t <sub>rem</sub>	_	2.0	5	ns
			4.5	5	
			6.0	5	
Clock frequency	f	_	2.0	4	MHz
			4.5	20	
			6.0	24	



## 13.7. AC Characteristics (Unless otherwise specified, $C_L$ = 15 pF, $V_{CC}$ = 5 V, $T_a$ = 25 °C, Input: $t_r$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Output transition time	$t_{TLH}, t_{THL}$	_	_	4	8	ns
Propagation delay time (CK-Qn)	t <sub>PLH</sub> ,t <sub>PHL</sub>	_	_	15	27	
Propagation delay time (CLR-Qn)	t <sub>PHL</sub>	_	_	16	30	
Maximum clock frequency	f <sub>MAX</sub>	_	33	58	_	MHz

## 13.8. AC Characteristics (Unless otherwise specified, $C_L = 50$ pF, $T_a = 25$ °C, Input: $t_r = t_f = 6$ ns)

Characteristics	Symbol	Note	V <sub>CC</sub> (V)	Min	Тур.	Max	Unit
Output transition time	$t_{TLH}, t_{THL}$		2.0	_	25	75	ns
			4.5	_	7	15	
			6.0	_	6	13	
Propagation delay time (CK-Qn)	t <sub>PLH</sub> ,t <sub>PHL</sub>		2.0	_	57	160	ns
			4.5	_	19	32	
			6.0	_	16	27	
Propagation delay time (CLR-Qn)	t <sub>PHL</sub>		2.0	_	60	175	ns
			4.5	_	20	35	
			6.0	_	17	30	
Maximum clock frequency	f <sub>MAX</sub>		2.0	6	18	_	MHz
			4.5	31	53	_	
			6.0	36	62	_	
Input capacitance	C <sub>IN</sub>		_	_	3	_	pF
Power dissipation capacitance	C <sub>PD</sub>	(Note 1)	_	_	30	_	pF

Note 1:  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation.  $I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{|N} + I_{CC}$ 

#### 13.9. AC Characteristics

(Unless otherwise specified,  $C_L = 50$  pF,  $T_a = -40$  to 85 °C, Input:  $t_r = t_f = 6$  ns)

Characteristics	Symbol	V <sub>CC</sub> (V)	Min	Max	Unit
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>	2.0	_	95	ns
		4.5	_	19	
		6.0		16	
Propagation delay time (CK-Qn)	t <sub>PLH</sub> ,t <sub>PHL</sub>	2.0		200	ns
		4.5	_	40	
		6.0	_	34	
Propagation delay time (CLR-Qn)	t <sub>PHL</sub>	2.0	_	220	ns
		4.5	_	44	
		6.0	_	37	
Maximum clock frequency	f <sub>MAX</sub>	2.0	5	_	MHz
		4.5	25		
		6.0	29		



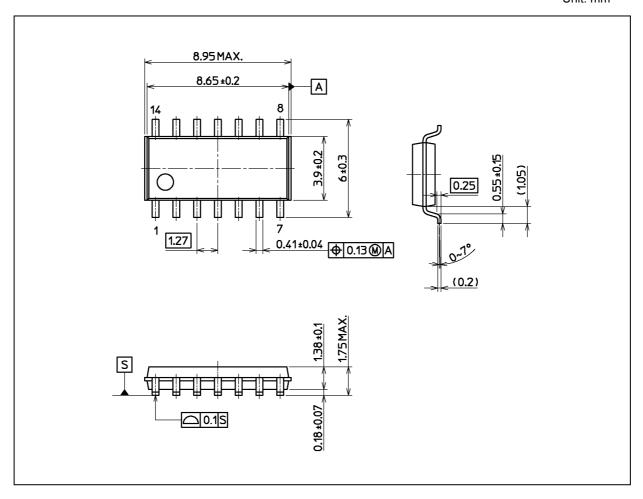
## 13.10. AC Characteristics (Unless otherwise specified, $C_L = 50$ pF, $T_a = -40$ to 125 °C, Input: $t_r = t_f = 6$ ns)

Characteristics	Symbol	V <sub>CC</sub> (V)	Min	Max	Unit
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>	2.0	_	110	ns
		4.5	_	22	
		6.0	_	19	
Propagation delay time (CK-Qn)	t <sub>PLH</sub> ,t <sub>PHL</sub>	2.0	_	240	ns
		4.5	_	48	
		6.0	_	41	
Propagation delay time (CLR-Qn)	t <sub>PHL</sub>	2.0	_	265	ns
		4.5	_	53	
		6.0	_	45	
Maximum clock frequency	f <sub>MAX</sub>	2.0	4	_	MHz
		4.5	20	_	
		6.0	24	_	



### **Package Dimensions**

Unit: mm



Weight: 0.13 g (typ.)

	Package Name(s)
Nickname: SOIC14	



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